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Karen Cinq-Mars 11/12/03
(Signature & date)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of _____: November 12, 2003
Edward Barth, et al. : Group Art Unit:
Serial No. _____: Examiner:
Filed: 11/12/03 _____: International Business Machines Corporation
2070 Route 52
Hopewell Junction, NY 12533

TITLE: ADVANCED BEOL INTERCONNECT STRUCTURES WITH LOW-K PE CVD CAP LAYER
AND METHOD THEREOF

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure set forth in 37 C.F.R. 1.56, and further pursuant to the provisions of 37 C.F.R. 1.97 and 1.98, applicants hereby respectfully submit copies of the non-US patents and publications as listed on Form PTO-1449, attached hereto.

In citing these documents, no representation is made nor intended as to the pertinency or non-pertinency of the art, that better art than that listed is not available, or that other art is not applicable.

No fee is believed to be due for this submission. If any fees are required, however, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 09-0458.

Respectfully submitted,
Edward Barth, et al.

By Margaret A. Pepper
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INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

ATTY DOCKET NO
FIS920010293US2

SERIAL NO.

Edward Barth et al.

FILING 11/12/03

GROUP

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5,679,169	10/21/1997	Gonzales et al.			
	6,080,529	06/27/2000	Ye et al.			
	6,150,258	11/21/2000	Mountsier et al.			
	6,153,523	11/28/2000	Van Ngo et al.			
	6,184,128 B1	02/06/2001	Wang et al.			
	6,184,572 B1	02/06/2001	Mountsier et al.			
	6,187,672 B1	02/13/2001	Zhao et al.			
	6,261,951 B1	07/17/2001	Buchwalter et al.			
	US 2001/0002333 A1	05/31/2001	Huang et al.			
	US 2001/0002731 A1	06/07/2001	Ueda			
	US 2001/0003064 A1	06/07/2001	Ohno			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

			Soo Geun Lee et al., "Low Dielectric Constant 3MS a-SiC:H as Cu Diffusion Barrier Layer in Cu Dual Damascene Process," Japanese Journal of Applied Physics, Part 1, Vol. 40, No. 4B, pp. 2663-2668, April 2001.
			2000 IEEE, A High performamnce 0.13um Copper BEOL Technology with Low-k Dielectric, R.D. Goldblatt et al., IBM Semiconductor Research and Development Center, Hopewell Junction, NY, Infineon Technologies Inc.

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

Docket Number (Optional)
FIS920010293US 2

Application Number

Applicant(s)
Edward Barth, et al.

Filing Date
November 12, 2003

Group Art Unit
Not Yet Assigned

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		6,071,809	06/2000	Zhao, Bin			
		6,420,261	07/2002	Kudo, Hiroshi			
		6,424,038	07/2002	Bao, et al.			
		US2003/0008493	01/2003	Lee			

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
		WO 99/33102	7/1/1999	PCT				
		FR2794286	12/1/2000	France				
		JP11330023A	11/30/1999	Japan				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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